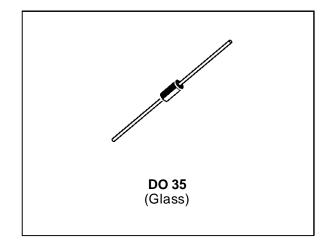


DB3 /DB4 / DC34

TRIGGER DIODES

FEATURES

- V_{BO}: 32V/34V/40V VERSIONS
- LOW BREAKOVER CURRENT



DESCRIPTION

High reliability glass passivation insuring parameter stability and protection against junction contamination.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
Р	Power dissipation on printed circuit (L = 10 mm)	Ta = 65 °C	150	mW
I _{TRM}	Repetitive peak on-state current	tp = 20 μs F= 100 Hz	2	А
Tstg Tj	Storage and operating junction temperat	- 40 to + 125 - 40 to + 125	္ခ <mark>္</mark> ခ	

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th (j-a)}	Junction to ambient	400	°C/W
R _{th (j-l)}	Junction-leads	150	°C/W

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ELECTRICAL CHARACTERISTICS $(Tj = 25^{\circ}C)$

Symbol	Parameter	Test Conditions		Value		Unit		
				DB3	DC34	DB4		
V _{BO}	Breakover voltage *			28	30	35	V	
		see diagram 1	TYP	32	34	40		
			MAX	36	38	45		
[I+V _{BO} I-I-V _{BO} I]	Breakover voltage symmetry	C = 22nF** see diagram 1	MAX	± 3			V	
IΔV± I	Dynamic breakover voltage *	$\Delta I = [I_{BO} \text{ to } I_{F}=10\text{mA}]$ see diagram 1	MIN	5			V	
Vo	Output voltage *	see diagram 2	MIN	5		V		
I _{BO}	Breakover current *	C = 22nF **	MAX	100	50	100	μА	
tr	Rise time *	see diagram 3	TYP	1.5		μs		
I _B	Leakage current *	V _B = 0.5 V _{BO} max see diagram 1	MAX		10		μА	

^{*} Electrical characteristic applicable in both forward and reverse directions.

DIAGRAM 1: Current-voltage characteristics

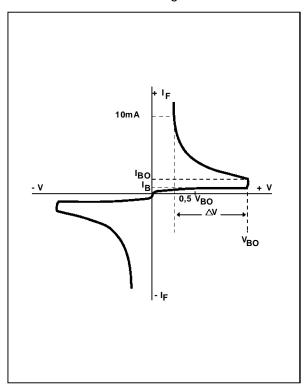


DIAGRAM 2: Test circuit for output voltage

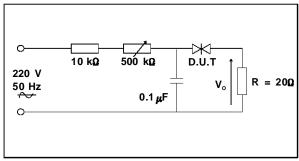
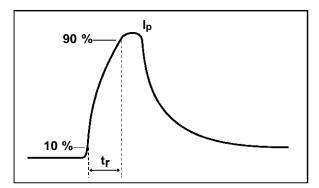


DIAGRAM 3 : Test circuit see diagram 2. Adjust R for lp=0.5A



^{**} Connected in parallel with the devices.

Fig.1: Power dissipation versus ambient temperature (maximum values)

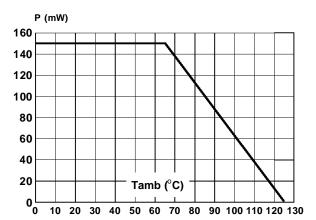


Fig.2 : Relative variation of V_{BO} versus junction temperature (typical values)

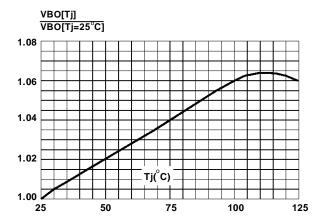
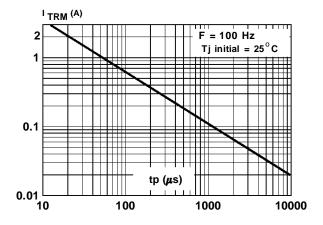
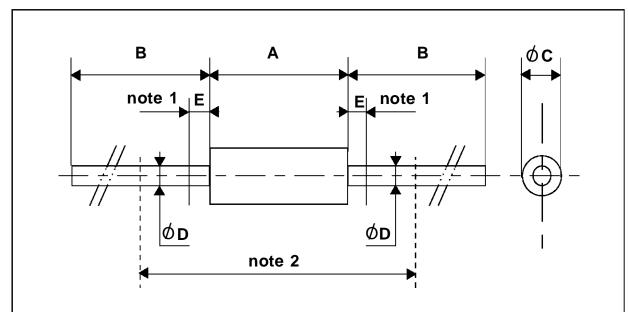


Fig.3: Peak pulse current versus pulse duration (maximum values)



PACKAGE MECHANICAL DATA (in millimeters)

DO 35 Glass



REF.	DIMENSIONS				NOTES		
	Millimeters Inches		Millimeters		hes		
	Min.	Max.	Min.	Max.			
Α	3.050	4.500	0.120	0.117	1 - The lead diameter Ø D is not controlled over zone E		
В	12.7		0.500		2 - The minimum axial lengh within which the device may be		
ØC	1.530	2.000	0.060	0.079	placed with its leads bent at right angles is 0.59"(15 mm)		
Ø D	0.458	0.558	0.018	0.022			
E		1.27		0.050			

Cooling method by convection and conduction

Marking: type number

Weight: 0.15 g

Polarity : N A Stud torque : N A

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